

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	36	(underfill or encapsulant or encapsulat\$3)same(substrate adj board)and clean\$3	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 14:00
L10	164	(underfill or encapsulant or encapsulat\$3)and(substrate adj board)and clean\$3	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 14:00
L11	30	((underfill or encapsulant or encapsulat\$3) same (clean\$3 wash\$3 or rins43))and(substrate adj board)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 14:01
L12	12	((underfill or encapsulant or encapsulat\$3 or resilient or resistant or resistance)near5 between near5(substrate adj board))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 14:05
S2	11	("5060844" "5784261" "6015722" "6048656" "6177728" "6294271" "6310120" "6333563" "6506869" "6572980" "6586846").PN.	US-PGPU B; USPAT	OR	ON	2006/10/03 17:50

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S3	10	S2 and (underfill or filler)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 17:57
S12	13	((solder or ball) near5 (interconnect or array)) and (underfill near50 filler)and (heat adj sink) and substrate and (interposer or stiffener) and (collar or bracket or support or frame or (rigid adj (metal or ball)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:43
S13	297	228/215.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:22
S14	488	228/178.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:22
S15	1089	228/180.1.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:22

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S16	978	228/180.21.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:22
S17	1264	228/180.22.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:24
S18	118	228/244.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:25
S19	3878	S13 or S14 or S15 or S16 or S17 or S18	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:26
S20	62	S19 and (interposer or stiffener) and (collar or bracket or support or frame or (rigid adj (metal or ball)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:27

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S22	23	S19 and underfill and (heat adj sink)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/03 18:44
S26	1444	((creep\$3 or fatigue or collapse\$3 or fall\$3 or bend\$3 or buckl\$3) adj resistan\$2)near5(collar or underfill or bracket or encapsulant or encapsulat\$3 or pin or metal))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 09:45
S27	358	S26 and (particle adj size)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 09:38
S28	496	S26 and (density)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 09:28
S29	332	S26 and (viscosity)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 09:28

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S30	50779	"228"/\$.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 09:43
S31	25	S30 and S26	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 09:43
S34	32	((creep\$3 or fatigue or collaps\$3 or fall\$3 or bend\$3 or buckl\$3) near5 resistan\$2)same(collar or underfill or bracket or encapsulant or encapsulat\$3 or pin or metal))same ((solder or ball) near5 (array or interconnect))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 10:22
S35	352652	"257"/\$.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 10:20
S36	17	S34 and S35	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 10:21

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S37	934	S35 and ((collar or underfill or bracket or encapsulant or encapsulat\$3 or pin or metal)near50 (vicosity or density or (particale adj size) or (glass adj transition adj temperature)))and ((solder or ball) near5 (array or interconnect))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 10:25
S38	112	S35 and (((collar or underfill or bracket or encapsulant or encapsulat\$3 or pin or metal)near50 (vicosity or density or (particale adj size) or (glass adj transition adj temperature)))near50 ((solder or ball) near5 (array or interconnect)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/05 10:25

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L16	630	((clean\$3 wash\$3 or rins\$3)same(substrate or board)same(prior or before or after)same(apply or applied or deposit\$3) same(underfill or encapsulant or encapsulat\$3))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/06 14:21
L17	20	((clean\$3 wash\$3 or rins\$3)with(substrate or board)with(prior or before or after)with(apply or applied or deposit\$3) with(underfill or encapsulant or encapsulat\$3))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/06 14:18
L18	40586	"228"/\$.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/06 14:21
L20	24	16 and 18	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/06 14:22